T Number				
L Numbe	r Hit 2253	- TORC	DB	Time stamp
-	2233	7 "MEMS"	USPAT;	2003/04/12 12:57
1	}		US-PGPUB	;
			EPO; JPO	;
			DERWENT;	
-	587	3 etching and recess and bonding	IBM_TDB USPAT;	2003/04/11 10 10
			US-PGPUB;	2003/04/11 10:48
1			EPO; JPO;	<u> </u>
1	1		DERWENT;	į
-	240	"MEMS" and (etching and recess and	IBM_TDB	
		bonding)	USPAT;	2003/04/11 11:03
			US-PGPUB; EPO; JPO;	
j	J		DERWENT;	
_	1576	microsensors	IBM TDB	1
	15/6	MICrosensors	USPAT;	2003/04/11 11:03
İ			US-PGPUB;	11103
1			EPO; JPO;	
			DERWENT;	
-	5488	sacrificial adj layer	IBM_TDB USPAT;	1
			US-PGPUB;	2003/04/11 11:04
	1		EPO; JPO;	1
İ			DERWENT;	1
-	914	"MEMC" and /	IBM TDB	1
	317	"MEMS" and (sacrificial adj layer)	USPĀT;	2003/04/11 11:04
			US-PGPUB;	
1			EPO; JPO;	j
			DERWENT; IBM TDB	j
-	69		USPAT;	3003 (04 (13
	İ	adj layer))	US-PGPUB;	2003/04/11 11:04
}			EPO; JPO;	1
			DERWENT;	İ
-	2627	"MEMS" and mirror	IBM_TDB	[
1		and million	USPAT;	2003/04/12 10:35
1	}		US-PGPUB;	
ĺ .	,		EPO; JPO; DERWENT;	1
i	611590		IBM TDB	
	011390	cavity	USPAT;	2003/04/12 10:35
ł j			US-PGPUB;	10.33
	[EPO; JPO;	
ĺ	1		DERWENT;	
-	744	("MEMS" and mirror) and cavity	IBM_TDB USPAT;	2002/04/05
İ	ĺ		US-PGPUB;	2003/04/12 10:38
ĺ			EPO; JPO;	
1	İ		DERWENT;] [
- 1	10978	substrate and sacrificial	IBM_TDB]
ł	1	and Suctificial	USPAT;	2003/04/12 10:39
1	ł		US-PGPUB;]
1	Ì		EPO; JPO; DERWENT;	ļ
_	175	// HMEMOH	IBM TDB]
ļ	1/5	(("MEMS" and mirror) and cavity) and	USPAT;	2003/04/12 10:49
		(substrate and sacrificial)	US-PGPUB;	10.49
			EPO; JPO;]
]		DERWENT;	
-	10114	variable adj capacitor	IBM TDB	0000 (0.5)
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ļ			EPO; JPO;	ľ
]	j		DERWENT;	
_ [224	"MPMC" and /	IBM TDB	1
1	224	"MEMS" and (variable adj capacitor)	USPĀT;	2003/04/12 10:50
•	1		US-PGPUB;	10.30
	1		EPO; JPO;	
			DERWENT;	į
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2	ļ				
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Tem TDB	1			EPO; JPO;	ľ
Silfingum Silf	ļ]		DERWENT;	1
30719 wafer and hydrogen USPAT; US-PGPUB; EPC; JPC; DPC; DPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; US-PGPUB; EPC; JPC	1 -	7774	"shin-etsu"	IBM TDB	1
S-PGPUB; EPO; JPO; DERWENT; IBM_TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB	1		Shith-etsu	USPAT;	2003/04/12 12:57
EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-P				US-PGPUB;	12.57
DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT				EPO; JPO;	
- 30719 wafer and hydrogen IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT;					1
Solid Water and hydrogen USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; DERWE	[-	30710	tinfon and had		
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB	1	30/19	water and nydrogen		2003/04/12 12:50
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO	ł				2003/04/12 12:38
Comparison	ļ			EPO: JPO:	1
1974 "shin-etsu" and (wafer and hydrogen) IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; US-PGPUB;	ļ			DERWENT	1
1974 Stacking adj faults USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US	_	C21			1
US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT;		631	"shin-etsu" and (wafer and hydrogen)		2003/04/12 10 50
1974 stacking adj faults EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; U	İ	ļ	,		2003/04/12 12:58
1974 stacking adj faults DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWE	ł			EPO: IPO:	1
1974 stacking adj faults IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPĀT; US-PGPUB; EPO; DERWENT; ISM_TDB USPĀT; US-PGPUB; EPO; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀT; USPĀ					1
42 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults) 42 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults) 43 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults) 44 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) 45 (("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) 46 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) 47 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) 48 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure)	ł]
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;	-	1974	stacking adj faults		1202242442
- 42 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults) - 3267641 vacuum or pressure 15 (("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;	}	İ			2003/04/12 12:58
- 42 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults) - 3267641 vacuum or pressure 15 (("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	ļ	Í			
- 42 ("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults) - 3267641 vacuum or pressure 15 (("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; DERWENT; DERWENT; DERWENT; US-PGPUB; EPO; JPO; DERWENT; DERW					1
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- 3267641 vacuum or pressure DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; USPĀPUB; EPO; JPO; DERWENT;		i	• • •	US-PGPUB;	1
- 3267641 vacuum or pressure IBM_TDB_USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	ĺ	1		EPO; JPO;	1
USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	ĺ	1			i i
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; and (stacking adj faults)) and (vacuum or pressure) US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	3267641	vacuum or pressure		1
- 15 (("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) (US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;		[]	•		2003/04/12 13:12
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(("shin-etsu" and (wafer and hydrogen)) and (stacking adj faults)) and (vacuum or pressure) IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;		i			,
and (stacking adj faults)) and (vacuum or pressure) USPĀT; US-PGPUB; EPO; JPO; DERWENT;					ļ
pressure) Stacking adj faults) and (vacuum or US-PGPUB; EPO; JPO; DERWENT;	-	15	(("shin-etsu" and /wafor and budgets		
pressure) pressure) DERWENT;			and (stacking add faults))		2003/04/12 13:12
EPO; JPO; DERWENT;			pressure)	US-PGPUB;	
		i i		EPO; JPO;	
IBM TDB		1	,		
				IBM TDB	